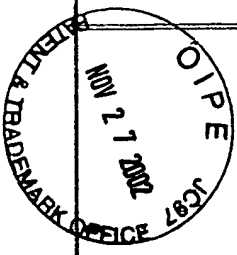


The comparisons of the characters on the process and the structure



The differences on the structure

Present Invention	Ohsawa et al.
<p>base metal</p> <p>insulating resin later-1</p> <p>electroless plating layer</p> <p>plating resist</p> <p>plated copper</p> <p>insulating resin later-2</p> <p>the wiring pattern</p> <p>making balls by electro-plating</p> <p>base metal</p> <p>insulating resin</p> <p>base metal is insulated from wired circuits</p> <p>removing base metal</p>	<p>base metal</p> <p>plating resist</p> <p>plated copper</p> <p>insulating layer</p> <p>the wiring pattern</p> <p>making balls by electro-plating</p> <p>base metal</p> <p>base metal wired circuits are electrically short circuited.</p> <p>removing base metal</p>

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The differences on the utility

- The functions of base metal can be utilized to the utmost limit
1. Base metal can be utilized as power and ground
 2. Base metal can be utilized as heat spreaders
 3. Base metal can be utilized as connecting terminals

The base metal has be removed to avoid a electrical structure.

The function can not be utilized

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